



# SMTA China East 华东高科技会议 Technical Conference

**25<sup>th</sup> April 2017 (Tuesday) / 2017 年 4 月 25 日(星期二)**

<b>(CE17-TC1) Technology Conference / 高科技技术研讨会</b>		
<b>Conference Chairman/会议主席:</b> Henley Zhou 周辉 <i>Member of SMTA China Technical Advisory Committee / 中国 SMTA 技术顾问委员会委员</i> <i>Director of Advanced Manufacturing Engineering, Asia of Flex</i> 伟创力亚洲区先进制造工程部总监		
<b>Venue/地点</b>	Room No.6, B2, Shanghai World Expo Exhibition & Convention Center 上海世博展览馆地下二层 6 号会议室	
<b>Time/时间</b>	<b>Topic/主题</b>	<b>Speaker/演讲者</b>
10:30 – 11:05	Stencil Aperture Area Ratio Extension – Impact of Stencil Technology and Coating 钢板开孔面积比扩展 - 钢板工艺与涂层的影响 (CE17-TC1.1)	Tim C.C. Pan 潘俊杰 Wistron Technology InfoComm ( KunShan ) Co., Ltd. 纬创资通(昆山)有限公司
11:05 – 11:40	Using Rheology Measurement As A Potentially Predictive Tool for Solder Paste Transfer Efficiency and Print Volume Consistency 使用流变性测量作为焊膏转移效率和印刷量一致性的预测工具 (CE17-TC1.2)	William Yu 余瑜 Alpha Assembly Solutions 爱法组装材料
11:40 – 12:15	Computer Tomography From Microelectronics To Assembled Products 从微型电子器件到整机的CT扫描技术 (CE17-TC1.3)	Keith Bryant SMT Solutions Michael Tang 唐立云 YXLON International GmbH 依科视朗(北京)射线设备贸易有限公司
12:15– 13:45	<b>Lunch Break / 午餐</b>	
13:45 – 14:20	01005/008004 Components Assembly Challenge 01005/008004 元件装配的挑战 (CE17-TC1.4)	Wisdom Qu 瞿艳红 Indium Corporation (Suzhou) Co., Ltd. 钢泰科技(苏州)有限公司
14:20 - 14:55	The Study of The Effect of PTH diameter, Connection Type and Amount of Connected Copper On PTH Hole Fill Percentage By Wave Soldering 关于波峰焊 PTH 孔径和热隔离类型以及连接铜量对填充高度影响的研究 (CE17-TC1.5)	Henley Zhou 周辉 Flex 伟创力
14:55 - 15:30	Surface Insulation Resistance of No-Clean Flux Residues Under Various Surface Mount Components 不同表面贴装元件下免洗助焊剂残留物对表面绝缘电阻影响 (CE17-TC1.6)	Dr. Yanrong Shi 史严容博士 Kester Components Pte Ltd. 凯斯特配件私人有限公司
15:30 - 16:05	Reflow Profile Repeatable and Consistency Analysis 回流焊炉温重复性和稳定性分析 (CE17-TC1.7)	Deyou Wu 吴德友 Jabil Circuit (Wu Xi) Co.,Ltd. 捷普电子无锡有限公司

**All papers will be presented in Chinese 所有演讲者都将使用中文**



# SMTA China East 华东高科技会议 Technical Conference

26<sup>th</sup> April 2017 (Wednesday) / 2017 年 4 月 26 日(星期三)

(CE17-TC2) Technology Conference / 高科技技术研讨会		
<b>Conference Chairman/会议主席:</b> Dong Lin 董林 Member of SMTA China Technical Advisory Committee / 中国 SMTA 技术顾问委员会委员 Section Manager, SMT Engineering of Artesyn Embedded Technologies 雅特生科技表面贴装工程分部经理		
<b>Venue/地点</b>	Room No.6, B2, Shanghai World Expo Exhibition & Convention Center 上海世博展览馆地下二层 6 号会议室	
<b>Time/时间</b>	<b>Topic/主题</b>	<b>Speaker/演讲者</b>
10:30 – 11:05	Soldering Immersion Tin 化学浸锡 - 焊接 (CE17-TC2.1)	Rick Nichols Atotech Deutschland GmbH
11:05 – 11:40	Enhanced Protection and Reliability of Harsh Environment Electronics Through Environment-Friendly, Insulating Conformal Coating (CE17-TC2.2)	Rakesh Kumar Specialty Coating System, Inc
11:40 – 12:15	Early Design Review of Boundary Scan and Test Coverage Analysis for Effective and Optimized Test Strategy 利用边界扫描法和测试覆盖率分析提早对设计进行审核, 实现高效和优化的测试策略 (CE17-TC2.3)	Sui Bin 睦宾 Keysight Technologies 是德科技公司
12:15 – 13:45	<b>Lunch Break / 午餐</b>	
13:45 – 14:20	Cleaning Agent Innovation for Highly Dense Electronic Assemblies 针对高密度电子组件的清洗剂创新 (CE17-TC2.4)	Daniel Gao 高伟 Kyzen Corporation 美国 Kyzen 公司
14:20 - 14:55	Progress In Low Temperature Lead-free Solder for SMT Assembly 无铅低温锡膏的发展与展望 (CE17-TC2.5)	Dr. Wayne Koh 葛唯恩博士 Pacrim Technology Inc. 美国加利福尼亚州环太科技公司
14:55 - 15:30	The FEA of Compressive Stress Strain of High Speed Connector Based On The Different PCB Surface Finishes 基于不同镀层的高速连接器压接应力应变仿真分析 (CE17-TC2.6)	Wang Dong 王栋 Fiberhome Telecommunication Technologies Co.,LTD 烽火通信科技股份有限公司
15:30 - 16:05	Application Methods and Thermal Mechanical Reliability of Polymeric Solder Joint Encapsulation Materials (SJEM) On SnAgCu Solder Joints 焊点加强的聚合物材料(SJEM)在 SnAgCu 焊接中的应用方法及热机械性能 (CE17-TC2.7)	Wang Xin 王鑫 Tech-Front(Shanghai)Computer Co. Ltd. 达丰(上海)电脑有限公司

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Fee / 收费: RMB300/per day (including official invoice) / 人民币 300 元/天(包含发票)

Noted: RMB285/per day for registering before 31 March and RMB540/two days for registering before 31 March

注: 在 3 月 31 日前登记会议可享受 9.5 折的优惠价, 同时报名登记 2 天的会议可享受 9 折的优惠价

Offer / 提供:

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